

DECLARATION FOR PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ELECTRONIC SURFACE MOUNT PACKAGE, the specification of which:

(check one) ☐ is attached hereto
☒ was filed on 8/10/95 as
Application Serial No.08/513,573
and was amended on October 9, 1996 and January 9, 1997

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information known to me to be material to patentability of this application as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: (none)

Prior Foreign Application(s)			<u>Priority Claimed</u>	
			<input type="checkbox"/>	<input type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No
			<input type="checkbox"/>	<input type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No.) (Filing Date) (Status)(patented, pending, abandoned)

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Direct all telephone calls to Stephen E. Baldwin at (415) 324-2258.

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18, United States Code, §1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: Peter Lu

Inventor's signature: 

Date: 5-19-97

Residence: 1708 Ingleside Drive, Flower Mound, TX 75028

Citizenship: U. S. Citizen

Post Office Address: 194 Civic Circle Lewisville, TX 75067

Full name of second joint inventor, if any: Jeffrey Heaton

Inventor's signature: 

Date: 5-19-97

Residence: 19832 Rodriques Cupertino, CA 95014

Citizenship: U. S. Citizen

Post Office Address: same

Full name of third joint inventor, if any: James W. Heaton

Inventor's signature: 

Date: 5-19-97

Residence: 1963 Fallen Leaf Lane, Los Altos, CA 94024

Citizenship: U.S. Citizen

Post Office Address: same

Full name of fourth joint inventor, if any: Peter Loh Hang Pao
Inventor's signature: *Peter Loh*
Date: 5/19/97
Residence: 10 Carnarvon Road, 8/F, A-1, Kowloon, Hong Kong
Citizenship: China
Post Office Address: same

Full name of fifth joint inventor, if any: Robert Loke Hang Lam
Inventor's signature: *Robert Loke*
Date: 5/19/97
Residence: Flat A, 6/F, Block 3, Wonderland Villas, N.T.,
Kowloon, Hong Kong
Citizenship: Hong Kong
Post Office Address: same

Full name of sixth joint inventor, if any: Tsang Kei Sun
Inventor's signature: *Ts. Kei Sun*
Date: 5/19/97
Residence: Flat F, 19/F, Tower One, Belvedere Garden, Phase Two,
Tsuen Wan, Kowloon, Hong Kong
Citizenship: Hong Kong
Post Office Address: same